TOSHIBA Field-Effect Transistor Silicon N Channel MOS Type

# SSM6N39TU

○ Power Management Switch Applications

- High-Speed Switching Applications
- 1.5-V drive
- N-ch 2-in-1
- Low ON-resistance:

 $R_{on} = 247 m\Omega (max) (@V_{GS} = 1.5 V)$ 

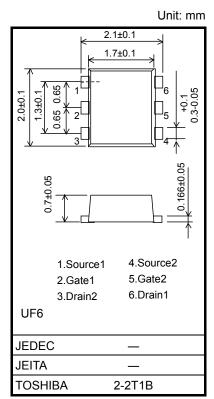
 $R_{on} = 190m\Omega (max) (@V_{GS} = 1.8 V)$ 

 $R_{on} = 139m\Omega \text{ (max)} (@V_{GS} = 2.5 \text{ V})$ 

 $R_{on} = 119m\Omega (max) (@V_{GS} = 4.0 V)$ 

#### Absolute Maximum Ratings (Ta = 25 °C) (Q1,Q2 Common)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	20	V	
Gate-source voltage		V <sub>GSS</sub>	± 10	V	
Drain current	DC	۱ <sub>D</sub>	1.6	A	
	Pulse	I <sub>DP</sub>	3.2		
Drain power dissipation		P <sub>D</sub> (Note1)	500	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	–55 to 150	°C	



Weight: 7.0mg (typ.)

Note: Using continuously under heavy loads (e.g. the application of

high temperature/current/voltage and the significant change in

temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: Mounted on an FR4 board. (total dissipation) (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm, Cu Pad : 645 mm<sup>2</sup> )

### Electrical Characteristics (Ta = 25°C) (Q1,Q2 Common)

Cha	aracteristics	Symbol	Test Conditions	Min	Тур.	Max	Unit	
Drain agurag bragkdawn yaltag-	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	20	—		v		
Drain-source breakdown voltage		V (BR) DSX	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = -10 V	12			v	
Drain cutoff currer	nt	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Gate leakage curr	rent	I <sub>GSS</sub>	$V_{GS}=\pm 10~V,~V_{DS}=0~V$	_		±1	μA	
Gate threshold vo	Itage	V <sub>th</sub>	$V_{DS} = 3 V, I_D = 1 mA$	0.35		1.0	V	
Forward transfer a	admittance	Y <sub>fs</sub>	$V_{DS} = 3 \text{ V}, \text{ I}_{D} = 1 \text{A} \qquad (\text{Note 2})$	2.5	5.0	_	S	
	Rds (ON)	$I_D = 1 \text{ A}, V_{GS} = 4.0 \text{ V}$ (Note 2)	_	87	119	- mΩ		
		$I_D = 1 \text{ A}, V_{GS} = 2.5 \text{ V}$ (Note 2)	_	105	139			
Drain-source ON-resistance		$I_D = 0.8 \text{ A}, V_{GS} = 1.8 \text{ V}$ (Note 2)	_	125	190			
		$I_D = 0.3 \text{ A}, V_{GS} = 1.5 \text{ V}$ (Note 2)	_	145	247			
Input capacitance Output capacitance		C <sub>iss</sub>			260		pF	
		C <sub>oss</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 0 V, f = 1 MHz	_	45	_		
Reverse transfer capacitance		C <sub>rss</sub>			37			
Total Gate Charge		Qg		_	7.5	_	nC	
Gate-Source Charge		Q <sub>gs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.6 A, V <sub>GS</sub> = 4 V		5.6			
Gate-Drain Charge		Q <sub>gd</sub>		_	1.9	_		
Switching time	Turn-on time	t <sub>on</sub>	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 0.5 A	_	8.3		ns	
	Turn-off time	t <sub>off</sub>	$V_{GS}$ = 0 to 2.5 V, $R_{G}$ = 4.7 $\Omega$	_	11.5	—		
Drain-source forward voltage		V <sub>DSF</sub>	I <sub>D</sub> = -1.6 A, V <sub>GS</sub> = 0 V (Note 2)	_	-0.8	-1.2	V	

Note 2: Pulse test

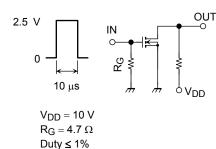
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#### **Switching Time Test Circuit**

(a) Test Circuit

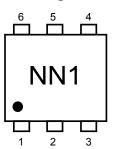
(b) V<sub>IN</sub>

(c) Vout

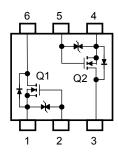


 $V_{IN}$ :  $t_r$ ,  $t_f < 5$  ns Common Source Ta = 25°C

Marking



Equivalent Circuit (top view)



#### **Usage Considerations**

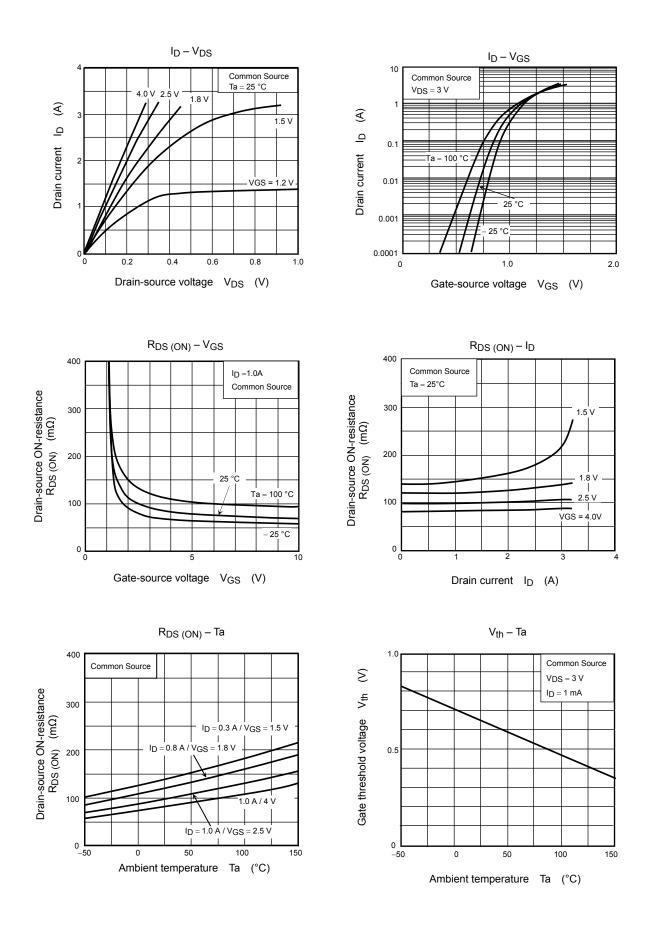
Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current (I<sub>D</sub>) to below (1 mA for the SSM6N39TU). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

#### **Handling Precaution**

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

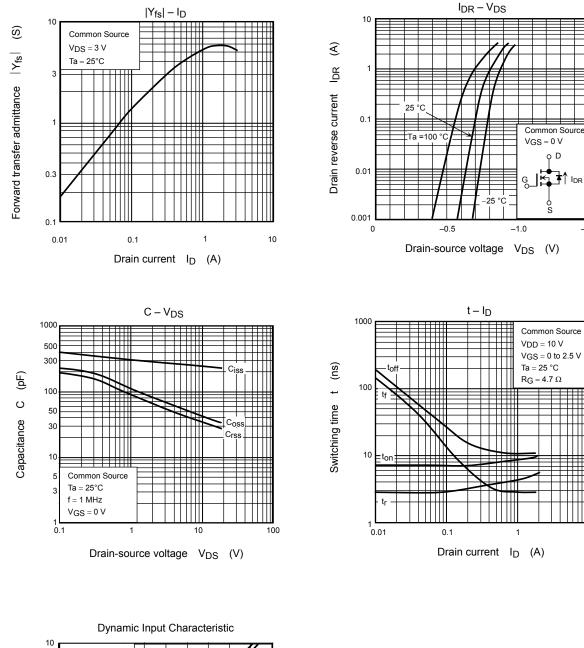
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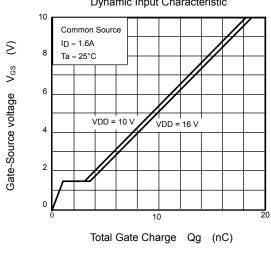


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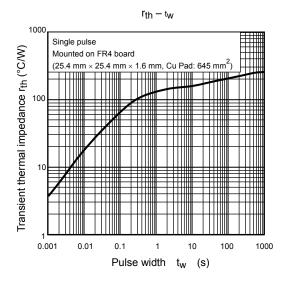
-1.5

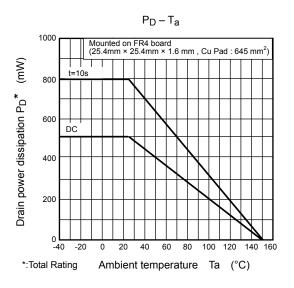
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